

ABSTRACT AMENDMENT

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Replace the Abstract with:

In a lead forming apparatus for a semiconductor device ~~according to the invention~~, a holder holds a semiconductor device with leads to be formed, the semiconductor device having leads extending from a package thereof. Two die assemblies (for bending, for cutting, or the like) are set in parallel, each ~~comprising a pair of~~ including top and bottom dies matched with each other. A mover changes a relative distance between the two die assemblies. The top and bottom dies in the two die assemblies are positioned ~~to interpose~~ so the leads of the semiconductor device held on ~~said the holder and form the leads~~ are between ~~them~~ the dies.